



# IEEE DTDA

2025 IEEE International Conference on  
Device Technologies for Diversified Applications

## Exhibit and Sponsor Prospectus

Dates: October. 20(Mon.)- 22(Wed.), 2025

Venue: TKP Gardencity Premium Sendai Nishiguchi(Miyagi, JAPAN)

*Sponsored by The IEEE Electron Devices Society(EDS)*

**Exhibitors and Sponsors****IEEE Device Technology for Diversified Applications (DTDA)**

The DTDA is a new flagship conference of the IEEE Electron Devices Society (EDS), will be held at TKP GardenCity, Sendai, Japan, from October 20th to 22nd, 2025, fully sponsored by EDS.

The DTDA distinguishes from other conferences, technologies are focusing on specific applications.

The conference will provide new approach to create closer relationship among the attendees including application sessions, interactive workshops, demo sessions, pitch and competition, art showcases.

Through these events, application meets technology, and new businesses will be innovating.

The success of the DTDA is strongly depends on conference contributors, especially exhibitors and sponsors. It would be really appreciated if you would contribute as exhibitors and/or sponsors. The conference brings exhibitors/sponsors strong connections with technology experts, suitable for specific application. Please enjoy the conference, it would help to enhance business opportunities.

**Shuji Ikeda**

General Chair of DTDA

**The Application Area****Application Area 1: Unleashing Power of MEMS**

Papers include practical MEMS and their applications for IoT, energy harvesting and power management, consumer electronics, telecommunications and 5G, as well as biomedical applications and environmental monitoring. Contributions are also encouraged on the role of MEMS in automotive and transportation systems, where they enhance safety and efficiency. Papers focused on advancements in MEMS fabrication and manufacturing are particularly welcome, as these innovations are essential for future realization.

**Application Area 2: Biosensors, Bioelectronics, Biomedical Devices**

Papers on the topics of biosensors, bioelectronics, medical devices, and healthcare monitoring are invited. The materials which are used for these devices include such as nanocarbon (CNTs, graphene, etc.), conductive materials, biocompatible polymers, hydrogels, and also DNA, proteins, and cells. The fabrication technologies of lithography, MEMS, laser fabrication, and also detection technologies of electrochemistry, optics, photonics, semiconductors are included.

**Application Area 3: Robotics for Smart Society**

Papers are invited in all areas of robotic technologies that enhance the quality of life, including assistive robots for home and healthcare, rehabilitation robots, and applications of robotics in telemedicine. Contributions on robots in smart factories that accelerate industrial automation, AI-driven optimization of production lines, and practical examples of collaborative robots are also welcomed. The scope of DTDA also includes applications of robots in education, AI-assisted teaching robots, robots in STEM education, and case studies from educational environments. Additionally, papers on robotic technologies for smart city infrastructure, optimization of public services, urban transportation systems, and security robots are encouraged. Submissions related to key components of practical robotic systems (AI, sensors, actuators, control systems, energy sources and efficiency, interface technologies) and their applications in various fields are highly welcome.

**Application Area 4: Automobile**

Inviting papers that will explore how these advancements shape the future of automotive technology. The automotive industry is rapidly advancing, driven by the integration of semiconductors to meet the demands of complex vehicle systems, electrification, and autonomous technologies. This call for papers seeks cutting-edge research on semiconductor innovations that enhance automotive safety, efficiency, and intelligence. Topics include advanced technologies addressing vehicle complexity, novel devices for next-gen applications, and the role of AI in automotive systems, such as adaptive driving aids and predictive maintenance. Join us in defining the future of automotive innovation.

**Application Area 5: Environmental Impact Mitigation, Energy Reduction and Water Risk Management**

Papers invited in all areas of environmental impact mitigation, energy reduction and water risk management. Latest environmental sustainability solutions including waste and emission reduction, recycling, green material development, life cycle assessment. Innovative energy efficiency approaches for energy-saving solutions including smart grids, renewable energy, energy harvesting. Best practices including water risk management and non-beneficial usage reduction, holistic approach to site water management, metrology, control of emerging contaminants (i.e., PFAS). Integrated strategies including environmental impact mitigation throughout the supply chain, balancing impact reduction with cost savings and risk, holistic and integrated approach to environmental footprint reduction.

**Application Area 6: Smart Agriculture on the Ground and in Space**

Papers include all area of sensing technologies for fully automated plant factories, plant growth that produces no waste, smart agriculture using as little water as possible and controlling harvest time and maintaining freshness of vegetables.

★ *Exhibition* (Demo)

The exhibition will be held on the same 6th floor as the pitches and various other events. You can interact with many active participants.

**Dates:** October 20 (Mon.) - 22 (Wed.), 2025

**Venue:** 6th floor, TKP Gardencity Premium Sendai Nishiguchi (Miyagi, JAPAN)

*Application  
Deadline*

**September  
12(Fri.),  
2025**

**Dates**

October 20 (Mon.), 21 (Tue.) 1:00pm - 7:00pm  
22 (Wed.) 9:00am - 4:00pm

**Installation**

October 20 (Mon.) 9:00am - 1:00pm

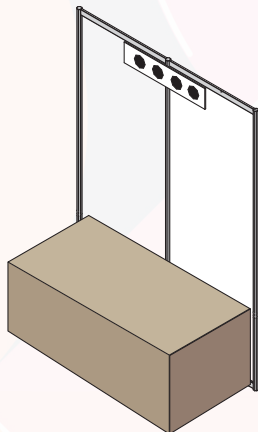
**Dismantling**

October 22 (Wed.) 4:00pm - 6:00pm

**Exhibition Fee : 200,000JPY**

**Benefits**

Each booth exhibitor is entitled to one complimentary full conference registration. Additional exhibitors are required to pay the registration fee to attend other DTDA technical sessions and events.

**Booth Specifications**

- Back panel : W1980 x H2400mm
- Company sign : 1
- Table : W1800 x D600 x H730mm
- Chair : 1
- Electricity Supply and Pricing (AC Single- Phase 100V 50Hz) : 500W
- 2 Electric outlets : 1

\*Please contact us for additional options, available for an additional fee.

**Venue Map: 6A and 6B: Exhibition**

The exhibition venue will host conference-sponsored pitches, workshops, and forums, providing a dynamic space for interaction and idea exchange.



6A

### ★ Budget and Sponsorship

We are pleased to invite you to join us as a sponsor for IEEE DTDA. Your support will greatly contribute to the success of this event, and we sincerely hope for your participation.

Plan	Fee		
	Platinum	Gold	Silver
	1,000,000JPY	500,000JPY	200,000JPY
Luncheon Seminar* *A first-come-first-served basis	✓	✓	✓
Company logo on the program book	✓	✓	✓
Advertisement of the company in the program book	1 Page	½ Page	½ Page
Company logo on official website, E-newsletter screen at session rooms	✓	✓	✓
Company logo featured on the banner at the venue	✓	✓	✓
Number of complementary full conference registration	10	5	2
Number of complementary short course Registration	10	5	2
Company Named Awards	✓		

### Inquiries for Exhibition and Sponsorship Nikkan Kogyo Communications Inc.

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Application Site

